

IN THE CLAIMS:

The status of the claims is as follows:

1-23. (Cancelled)

24. (Previously Presented): A method of forming a metal layer on a substrate, comprising:

positioning a substrate in an electroplating cell having a porous pad and an electrolyte solution therein;

contacting at least a portion of the substrate to the porous pad;

forming a metal layer on the substrate by biasing the substrate relative to an electrode at a first electrical bias and then biasing the substrate relative to the electrode at a second electrical bias, wherein the first electrical bias deposits metal on the substrate and the second electrical bias removes metal from the substrate; and

varying the magnitude of the second electrical bias relative to the first electrical bias as the metal layer is formed.

25. (Cancelled)